PCN Number:	201512160	01			P	CN Da	te:	12/17/2015	
Title: Datasheet f	for DRV2604								
<b>Customer Contact:</b>	PCN Manager				Dept:		Quality Services		
Change Type:								-	
Assembly Site			Design			Wafer	Bum	p Site	
Assembly Proces	SS	$\square$	Data Sheet			Wafer	Bum	p Material	
Assembly Materials			Part number change			Wafer	Bum	p Process	
Mechanical Specification			Test Site			Wafer	<sup>-</sup> Fab Site		
Packing/Shipping/Labeling			Test Process			Wafer	afer Fab Materials		
						Wafer Fab Process			
Notification Details									
<b>Description of Char</b>									
Texas Instruments In	corporated is a	ann	ouncing an information on	ly r	loi	tificatio	n etc		
The following change	., _		ited as summarized below Further details.						
Texas Instruments								DRV2604	
INSTRUMENTS			SLOS824B -	DECE	MB	ER 2012-RI	EVISED D	ECEMBER 2015	
Changes from Revision A	(July 2015) to Revi	sion	в					Page	
Changed t <sub>h(1)</sub> Hold time, SCL to SDA from 10 ns to 50 ns in Timing Requirements									
<ul> <li>Changed the default value</li> </ul>	ue of NG_THRESH[	1:0] f	rom 1 to 2 in the <i>Register Map</i>					45	
Device Family			Change From:	Change To:					
DRV2604			SLOS824A					<b>824B</b>	
DIW2001			320302 //						
These changes may h	a ravioused at	tha	datasheet links provided.						
http://www.ti.com/pr			datasheet miks provided.						
		<u></u>							
<b>Reason for Change</b>	:								
		nara	cteristics.						
Reason for Change To more accurately re	eflect device cl			hili	<b>†</b> 14	(nosi	tive	(negative):	
To more accurately re Anticipated impact	eflect device ch on Fit, Form,	, Fu	nction, Quality or Relia		_				
To more accurately re Anticipated impact No anticipated impac	eflect device ch on Fit, Form,	, Fu			_				
To more accurately re Anticipated impact No anticipated impac to the actual device.	eflect device ch on Fit, Form, t. This is a spe	, <b>Fu</b> cific	nction, Quality or Relia cation change announceme		_				
To more accurately re Anticipated impact No anticipated impac to the actual device. Changes to product	eflect device ch on Fit, Form, t. This is a spe	, <b>Fu</b> cific	nction, Quality or Relia		_				
To more accurately re Anticipated impact No anticipated impac to the actual device. Changes to product None.	eflect device ch on Fit, Form, t. This is a spe	, <b>Fu</b> cific	nction, Quality or Relia cation change announceme		_				
To more accurately re Anticipated impact No anticipated impac to the actual device. Changes to product	eflect device ch on Fit, Form, t. This is a spe	, <b>Fu</b> cific	nction, Quality or Relia cation change announceme		_				
To more accurately re Anticipated impact No anticipated impac to the actual device. Changes to product None.	eflect device ch on Fit, Form, t. This is a spe	, Fu cific	nction, Quality or Relia cation change announceme esulting from this PCN:		_				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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